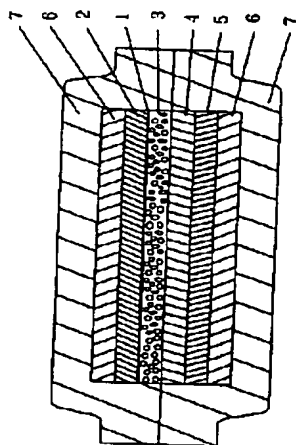


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CONSTITUTION: As an inorganic moisture absorbent, a white or transparent substance with the particle diameter 5 to 10. μm is used, and it is selected from zeolite, a silica gel, an active alumina, a calcium oxide, a barium oxide, and a silicon oxide. The moisture absorbent is mixed by 0.1 to 20wt.% in the weight of the phosphor in a phosphor layer 3. Since the amount of the moisture absorbed in the moisture absorbent is much more than the moisture absorbed in the phosphor, and the moisture absorbent absorbs the moisture near the phosphor, the phosphor is maintained in a dried condition to suppress its deterioration.



WPI Acc No: 1992-304460/ 199237

XRAM Acc No: C92-135449

XRPX Acc No: N92-233057

Moisture absorbing tiles for buildings - obtd. by moulding and drying

mixt. contg. silicic acid gel, fibrous material and adhesive

Patent Assignee: KIEZEL KK F (KIEZ-N)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 4210233	A	19920731	JP 90341015	A	19901130	199237 B

Priority Applications (No Type Date): JP 90341015 A 19901130

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 4210233	A		9	B01J-020/10	

Abstract (Basic): JP 4210233 A

A new moulding absorbing moisture is a composite obtd. by moulding and drying a mixt. contg. at least 50 wt.% silicic acid gel (A), 10-30 wt.% fibrous material (B), and up to 30 wt.% of adhesive (C).

A method for removing moisture from floors or walls is also claimed, where a number of tiles made of the new moulding are put on the floors or walls.

Pref. the moulding contains up to 20 wt.% alkaline earth metal halide besides (A), (B), and (C). MATERIAL - 'Fuji Silicagel Type-A, B, RD, or AB' (RTM, Fuji-Devison Corp.) is suitably used. Sawdust chips (2-3 mm) or wastepaper (5 mm) are used as (B). (C) is hydrophilic vinyl chloride, vinyl acetate, or PVA emulsion. The alkaline earth metal halide includes CaCl_2 or MgCl_2 .

USE/ADVANTAGE - Used as a construction material for drying houses or buildings. The moulding is easy to handle

Dwg. 0/9

Title Terms: MOIST; ABSORB; TILE; BUILD; OBTAIN; MOULD; DRY; MIXTURE;
CONTAIN; SILICIC; ACID; GEL; FIBRE; MATERIAL; ADHESIVE

Derwent Class: A93; J01; Q43

International Patent Class (Main): B01J-020/10

International Patent Class (Additional): B01D-053/26; B01J-020/28;

E04B-001/64

File Segment: CPI; EngPI

Manual Codes (CPI/A-N): A12-R01; J01-E01; J01-E03C

Plasdoc Codes (KS): 0209 0231 0759 0787 2007 2504 2682 2691 2694 2696 3250
3316

Polymer Fragment Codes (PF):

001 014 04- 061 062 063 066 067 231 244 245 397 436 52& 532 533 535 54&
609 613 614 616 678 688

WPI Acc No: 1994-179394/ 199422

XRPX Acc No: N94-141356

EL device with back electrode and carbon-metal conductive paste layer -
provides surface opposite to back electrode insulation layer with
moisture capturing layer NoAbstract

Patent Assignee: SEIKOSHA KK (SUWB)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 6119970	A	19940428	JP 92264743	A	19921002	199422 B

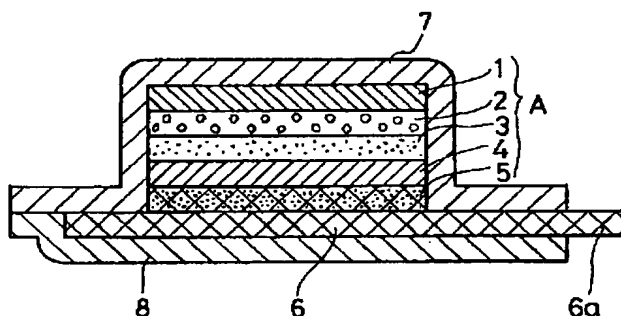
Priority Applications (No Type Date): JP 92264743 A 19921002

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 6119970	A		4	H05B-033/04	

Abstract (Basic): JP 6119970 A

Dwg. 1/1



Title Terms: ELECTROLUMINESCENT; DEVICE; BACK; ELECTRODE; CARBON; METAL;